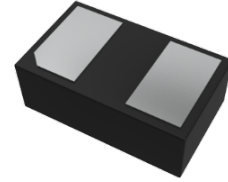


Features

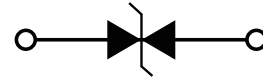
- Low leakage current
- Low clamping voltage
- IEC 61000-4-2 (ESD Air): $\pm 25\text{kV}$
- IEC 61000-4-2 (ESD Contact): $\pm 20\text{kV}$
- IEC 61000-4-5 (Lightning 8/20 μs): 5A



DFN1006-2L

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation, Digital Cameras
- Peripherals, Audio Players, Industrial Equipment

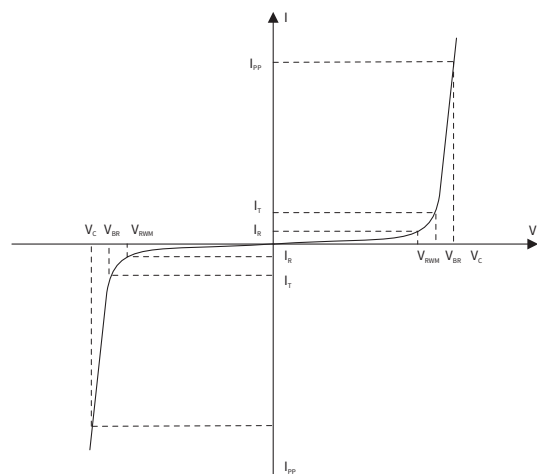


Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V _{ESD}	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2(Air)	± 25	KV
		ESD per IEC 61000-4-2(Contact)	± 20	KV
P _{pp}	Peak Pulse Power	tp = 8/20 μs	125	W
I _{pp}	Rated Peak Pulse Current	tp = 8/20 μs	5	A
T _J	Operating JunctionTemperature Range	—	-55 to +125	°C
T _{STG}	Operating JunctionTemperature Range	—	-55 to +150	°C

Electrical Parameter

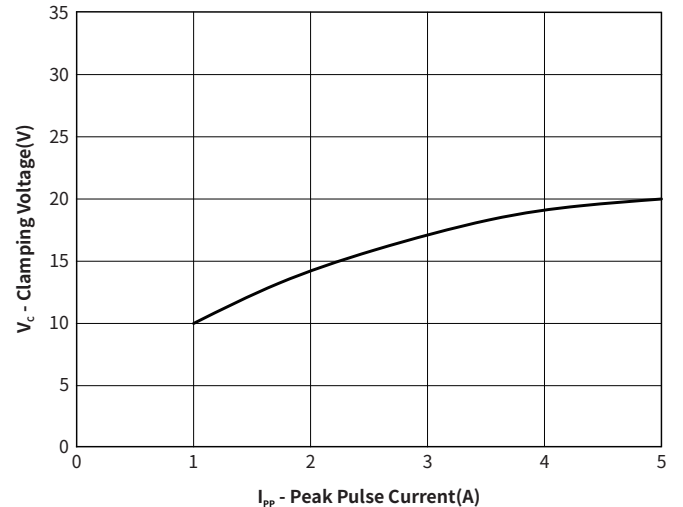
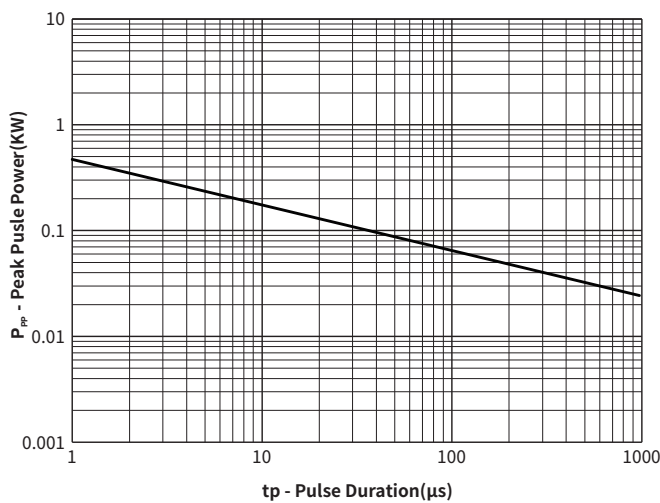
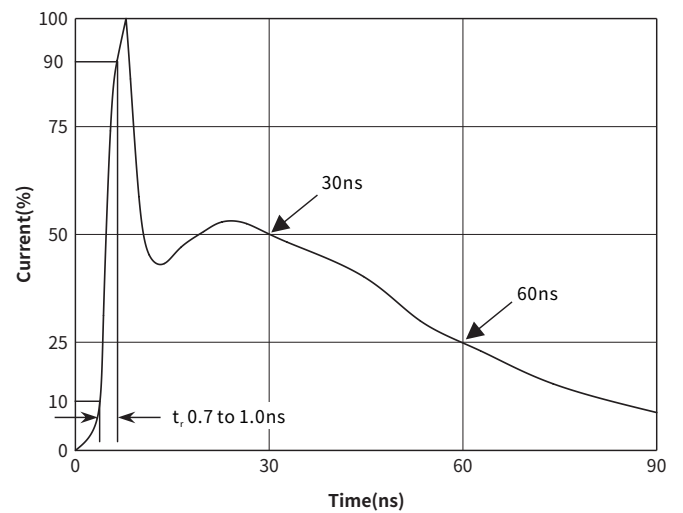
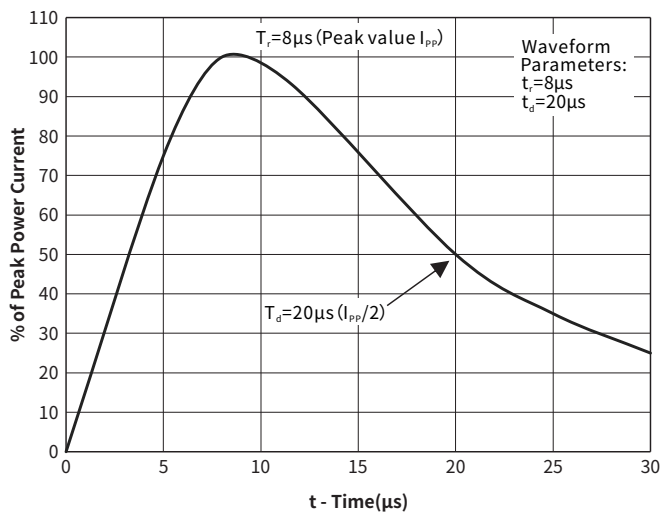
SYMBOL	PARAMETER
V _C	Clamping Voltage @ I _{pp}
V _{BR}	Breakdown Voltage @ I _T
I _{pp}	Peak Pulse Current
I _T	Test Current
I _R	Reverse Leakage Current @ VRWM
V _{RWM}	Peak Reverse Working Voltage
P _{pp}	Peak Pulse Power Dissipation
C _J	Junction Capacitance @ V _R =0V,f=1MHz
I _F	Forward Current
V _F	Forward Voltage @ I _F



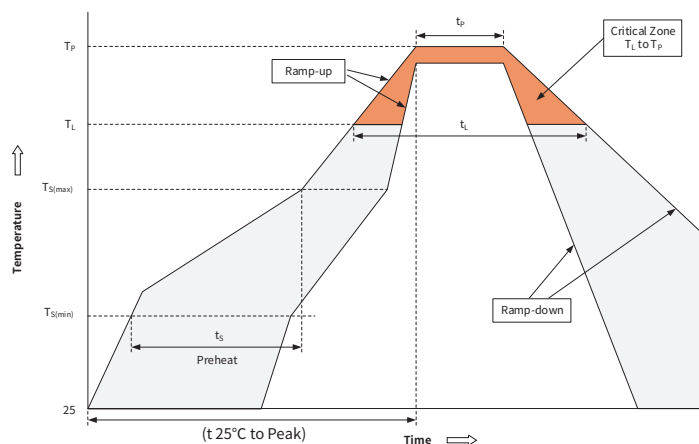
Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	V_{RWM}	$T_a=25^{\circ}\text{C}$	—	—	3.3	V
Breakdown Voltage	V_{BR}	$I_T=1.0\text{mA}, T_a=25^{\circ}\text{C}$	5	—	9	V
Reverse Leakage Current	I_R	$V_{RWM}=3.3\text{V}, T_a=25^{\circ}\text{C}$	—	—	0.2	μA
Clamping Voltage	V_C	$I_{PP}=1.0\text{A}, t_p=8/20\mu\text{s}$	—	—	11	V
		$I_{PP}=5.0\text{A}, t_p=8/20\mu\text{s}$	—	—	25	
Junction Capacitance	C_J	$V_{RWM}=0\text{V}, f=1\text{MHz}$	—	0.25	0.3	pF

Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)

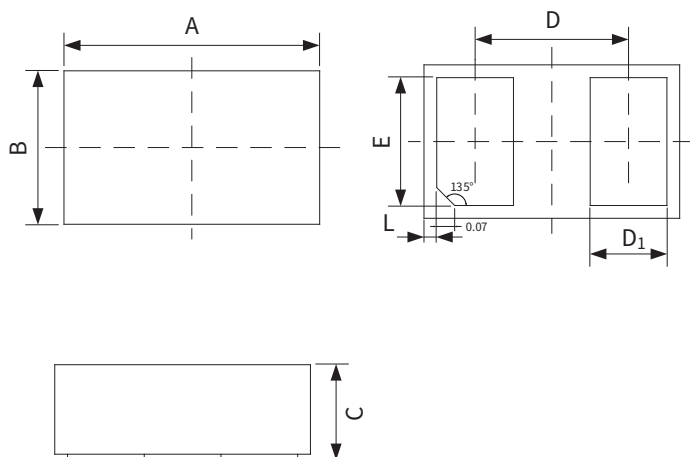


Recommended Soldering Conditions



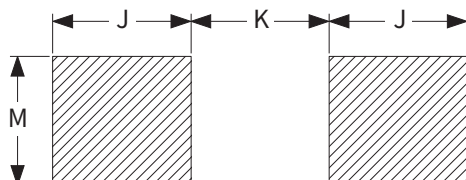
Profile Feature		Pb-Free Assembly
Pre-heat	Temperature Min ($T_{S(min)}$)	+150°C
	Temperature Max ($T_{S(max)}$)	+200°C
	Time (Min to Max) (t_S)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C /sec. Max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C /sec. Max
Reflow	Temperature(T_L)(Liquid us)	+217°C
	Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		20-40secs
Ramp-down Rate		6°C /sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

Package Outline Dimensions (DFN1006)



Symbol	Dimensions			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.950	1.050	0.037	0.041
B	0.550	0.650	0.022	0.026
C	0.350	0.450	0.014	0.018
D	0.550	0.650	0.022	0.026
D ₁	0.280	0.380	0.011	0.015
E	0.450	0.550	0.018	0.022
L	0.000	0.100	0.000	0.004

Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min	Max	Min	Max
J	0.50	0.60	0.020	0.024
K	0.25	0.35	0.010	0.014
M	0.55	0.65	0.022	0.026